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## Declaration and Power of Attorney for Patent Application

## English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled PRINTED WIRING BOARD, MANUFACTURING PROCESS AND CIRCUIT DEVICE The specification of which is attached hereto. was filed on \_\_\_  $\Box$ as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_ (if applicable) was filed as PCT international application X No. PCT/JP2004/17945 on December 2, 2004 and was amended under PCT Article 19 on \_\_ (if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)				Priority Claimed	
2003-407540	Japan	5 December 2003	X	0	
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No	
2004-222184	Japan	29 July 2004	Χı	0	
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No	
(Number)	(Country)	(Day/Month/Year Filed)	□ Yes	D No	

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.)	- (Fil	ing Date)	-	(Status) (patented, pending, abanc	loned)	
(Application Serial No.)	- (Fil	ing Date)	-	(Status) (patented, pending, abanc	loned)	
I hereby declare that all st on information and believe knowledge that willful faboth, under Section 1001 jeopardize the validity of	f are believed llse statements of Title 18 of	I to be true; and furthe s and the like so made f the United States Coo	er that the are punited and that	ese statements were mad shable by fine or imprise	e with the onment, or	
POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name and registration number)						
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Full name of sixth joint inventor, if any	
Tun name or sixingenic inventor, is any	
Inventor's signature	Date
Residence	
Citizenship	,
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